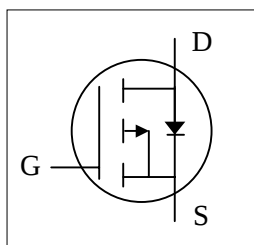


- ▼ 100% R_g & UIS Test
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free

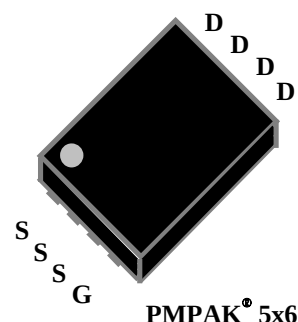


BV _{DSS}	-30V
R _{DS(ON)}	8mΩ

Description

XP4463 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The PMPAK[®] 5x6 package is special for voltage conversion application using standard infrared reflow technique with the backside heat sink to achieve the good thermal performance.



Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±25	V
I _D @T _C =25°C	Drain Current, V _{GS} @ 10V	-66	A
I _D @T _C =100°C	Drain Current, V _{GS} @ 10V	-41	A
I _D @T _A =25°C	Drain Current, V _{GS} @ 10V ³	-20.8	A
I _D @T _A =70°C	Drain Current, V _{GS} @ 10V ³	-16.7	A
I _{DM}	Pulsed Drain Current ¹	-260	A
P _D @T _C =25°C	Total Power Dissipation	50	W
P _D @T _A =25°C	Total Power Dissipation ³	5	W
E _{AS}	Single Pulse Avalanche Energy ⁴	80	mJ
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
R _{thj-c}	Maximum Thermal Resistance, Junction-case	2.5	°C/W
R _{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	25	°C/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-20A	-	-	8	mΩ
		V _{GS} =-4.5V, I _D =-12A	-	-	15	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-1	-	-3	V
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-20A	-	40	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V	-	-	-10	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge ⁵	I _D =-20A	-	43	68.8	nC
Q _{gs}	Gate-Source Charge ⁵	V _{DS} =-15V	-	9	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge ⁵	V _{GS} =-10V	-	10	-	nC
t _{d(on)}	Turn-on Delay Time ⁵	V _{DS} =-15V	-	12	-	ns
t _r	Rise Time ⁵	I _D =-1A	-	11	-	ns
t _{d(off)}	Turn-off Delay Time ⁵	R _G =3.3Ω	-	100	-	ns
t _f	Fall Time ⁵	V _{GS} =-10V	-	74	-	ns
C _{iss}	Input Capacitance ⁵	V _{GS} =0V	-	2420	3872	pF
C _{oss}	Output Capacitance ⁵	V _{DS} =-25V	-	410	-	pF
C _{rss}	Reverse Transfer Capacitance ⁵	f=1.0MHz	-	245	-	pF
R _g	Gate Resistance	f=1.0MHz	-	11	22	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =-20A, V _{GS} =0V	-	-	-1.2	V
t _{rr}	Reverse Recovery Time ⁵	I _S =-20A, V _{GS} =0V, dI/dt=100A/μs	-	15	-	ns
Q _{rr}	Reverse Recovery Charge ⁵		-	5	-	nC

Notes:

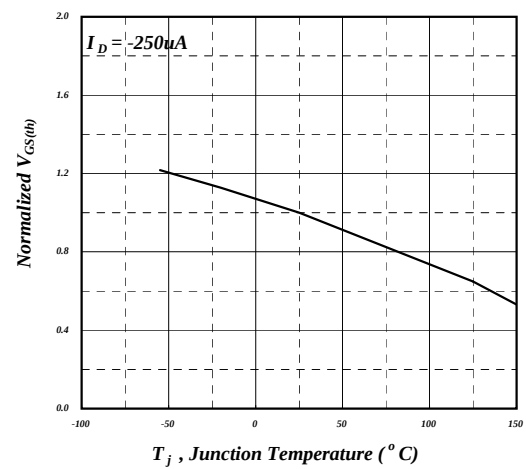
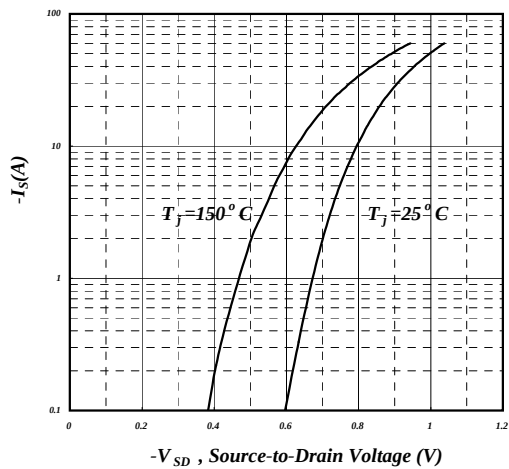
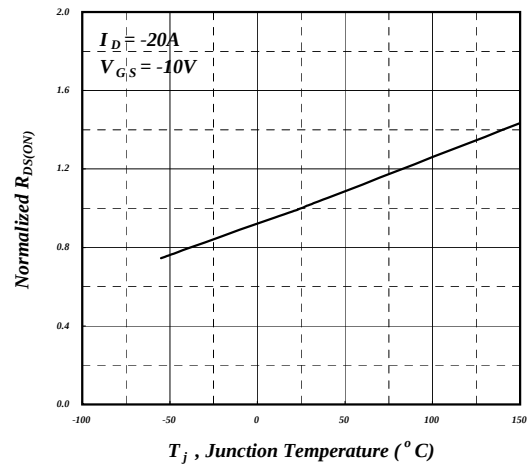
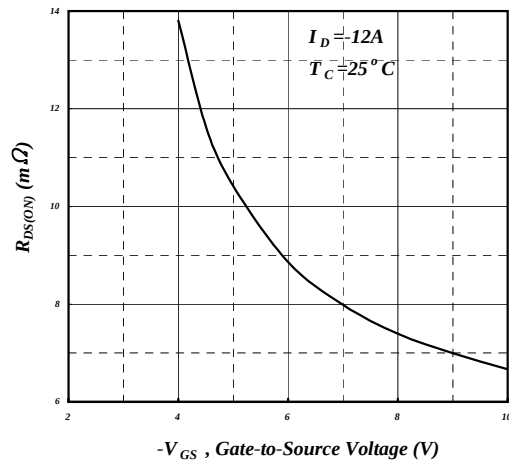
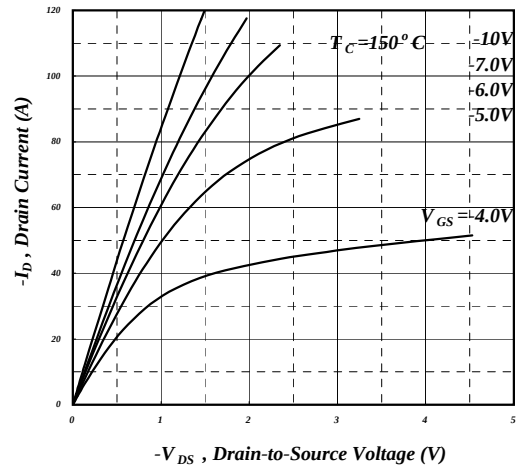
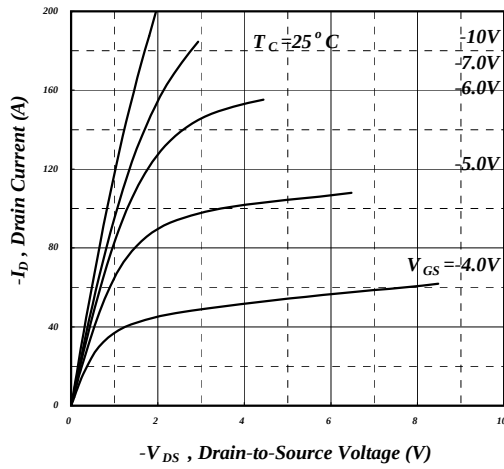
- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤10sec ; 60°C/W at steady state.
- 4.Starting T_j=25°C , V_{DD}=-30V , L=0.1mH , R_G=25Ω , V_{GS}=-10V
- 5.Guaranteed by design.
- 6.These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150°C.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT, AUTOMOTIVE OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

XSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.



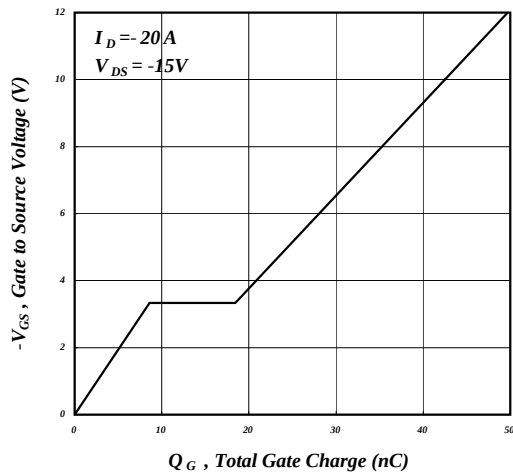


Fig 7. Gate Charge Characteristics

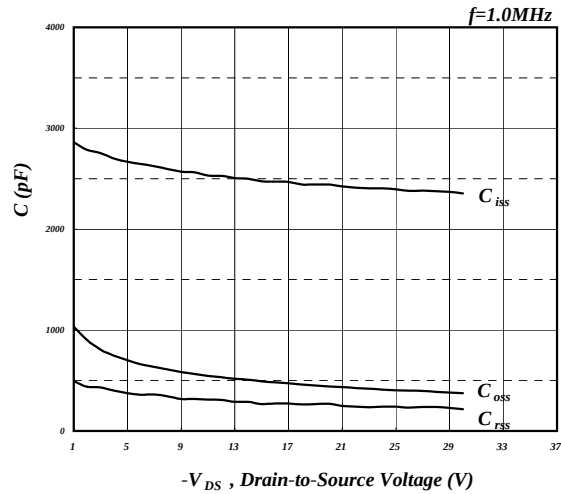


Fig 8. Typical Capacitance Characteristics

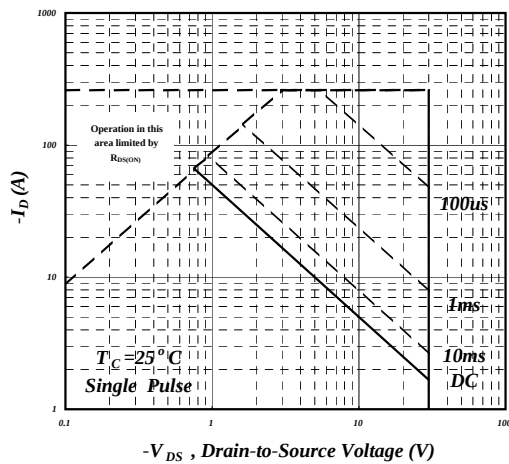


Fig 9. Maximum Safe Operating Area⁶

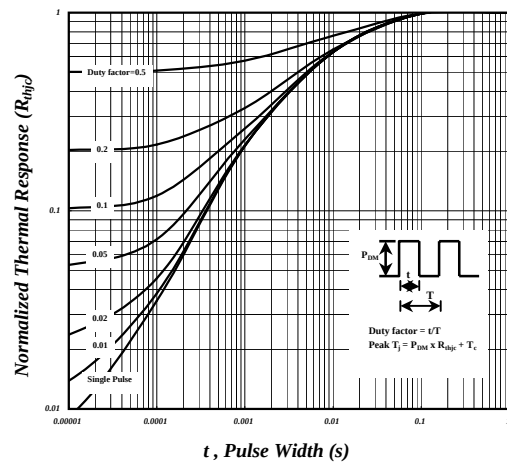


Fig 10. Effective Transient Thermal Impedance

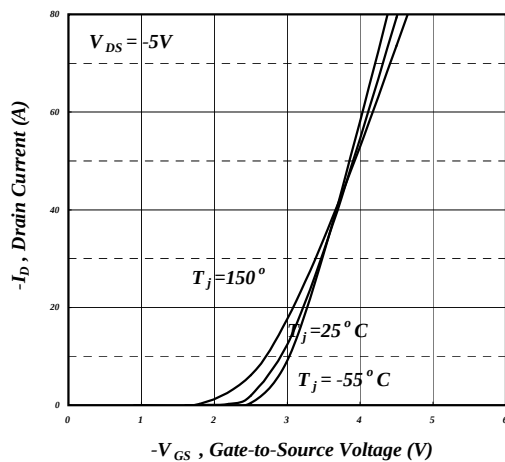


Fig 11. Transfer Characteristics

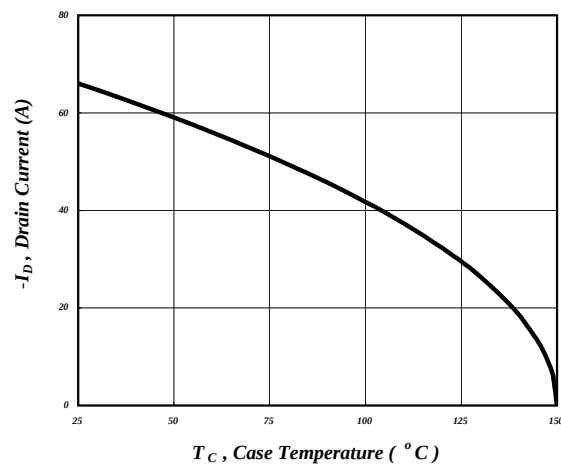


Fig 12. Drain Current v.s. Case Temperature

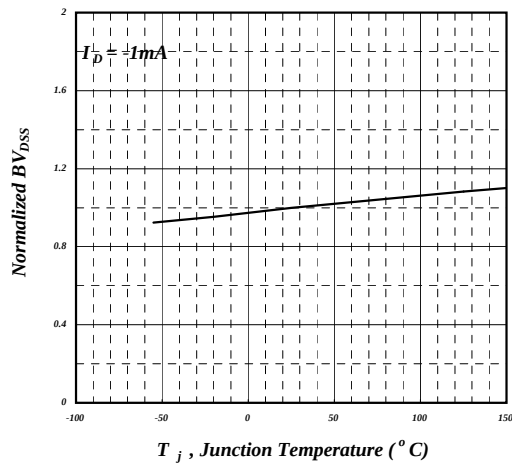


Fig 13. Normalized BV_{DSS} v.s. Junction Temperature

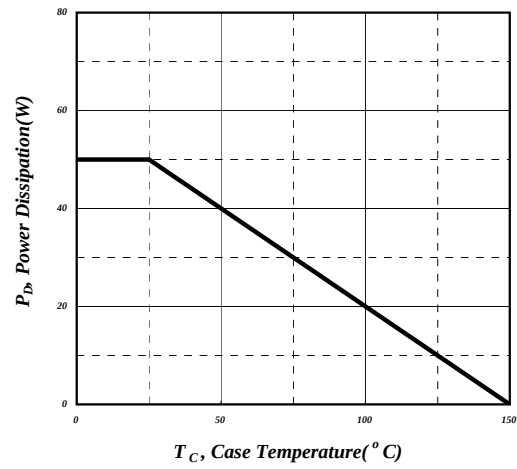


Fig 14. Total Power Dissipation

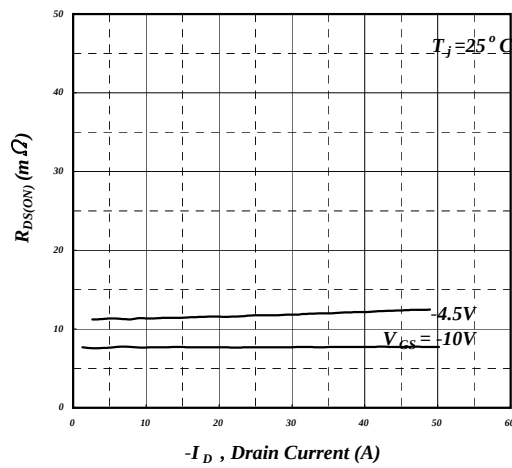
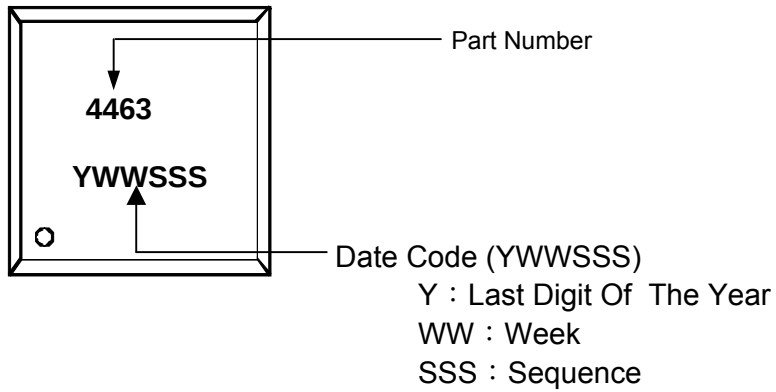
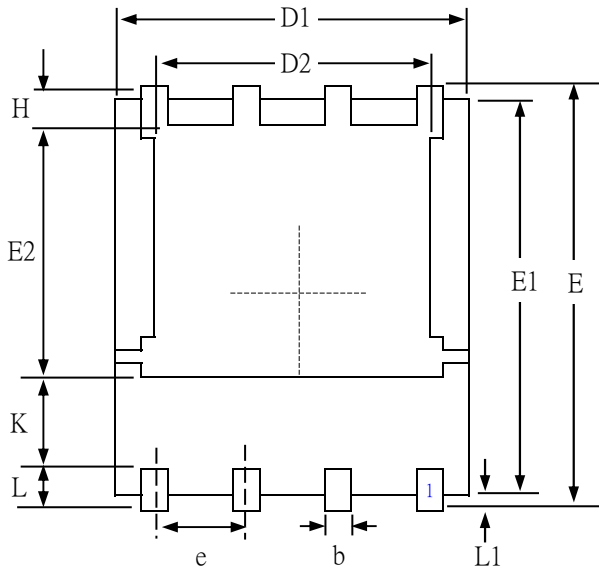


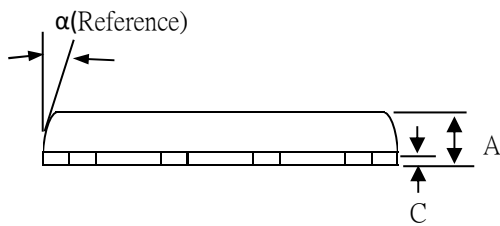
Fig 15. Typ. Drain-Source on State Resistance

MARKING INFORMATION

Package Outline : PMPAK 5x6



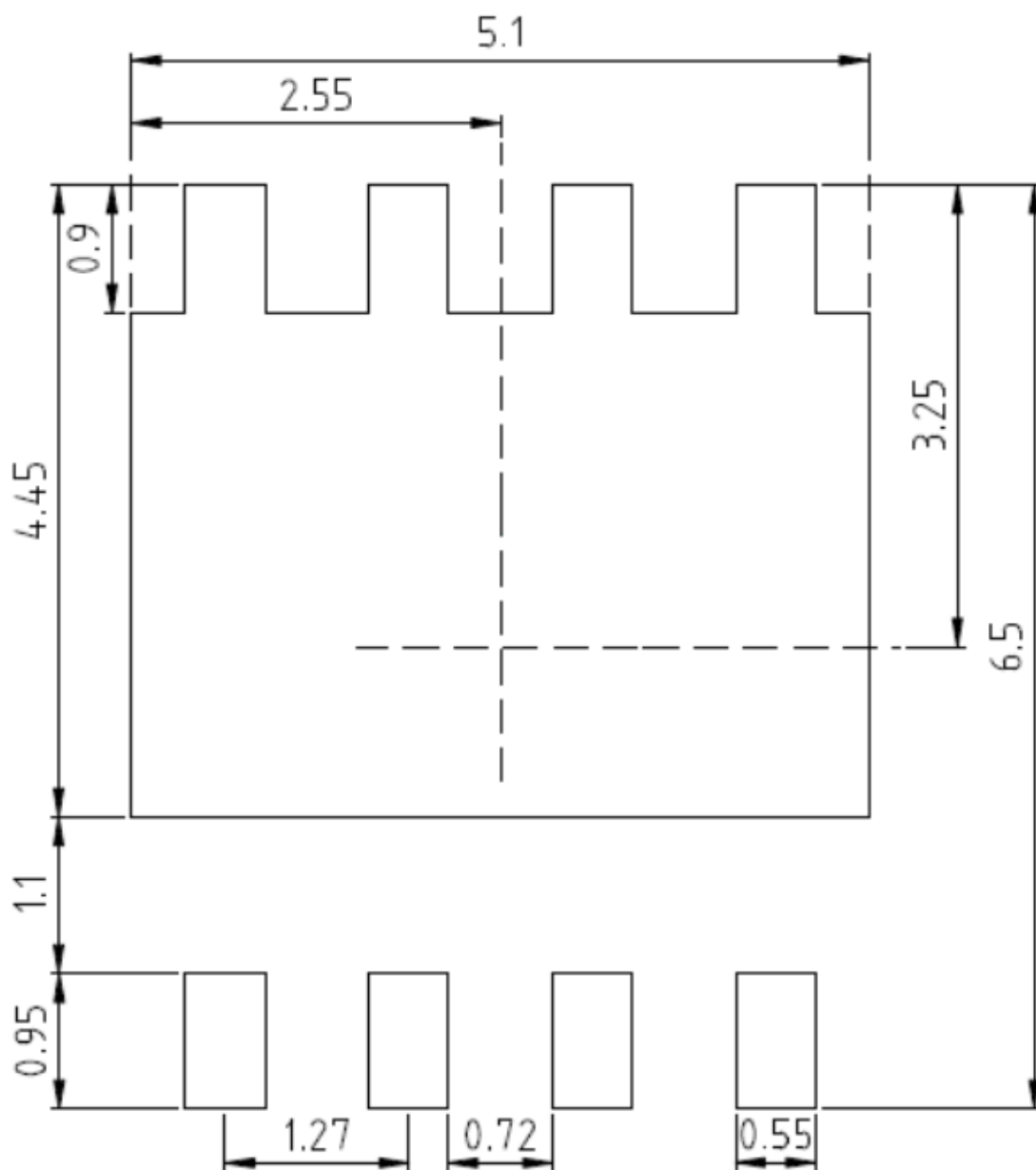
BACKSIDE VIEW



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	0.90	1.10	1.30
b	0.33	0.41	0.51
C	0.254(Ref.)		
D1	4.80	4.90	5.10
D2	3.61	4.00	4.40
E	5.80	6.03	6.25
E1 (Ref.)	5.60	5.75	5.90
E2 (Ref.)	3.30	3.55	3.80
e	1.27 BSC		
H	0.35	—	0.90
K (Ref.)	1.00	1.275	—
L	0.35	0.55	0.75
L1	0.06	0.13	0.20
α (Ref.)	0°	—	12°

- 1.All dimension are in millimeters.
- 2.Dimension does not include burrs and mold flash/protrusions.
- 3.The outline schematic is not to scale and slightly different from the actual product appearance.

PMPAK 5X6(E-TYPE) FOOTPRINT :



UNIT: mm